

## C7403 - C7404A

### Conductor

#### Description

C7403 / C7404A is a ENIG plateable, wire bondable copper conductor system developed for applying thick layers of copper. It is optimized for lapped AlN substrates as well as 96 % alumina. It is intended for use where cost sensitive applications involving high thermal and electrical properties are required. C7403 / C7404A are applied by screen printing, dried in air and fired in a nitrogen atmosphere. C7403 is applied by printing as the base layer. C7404A is printed on top of C7403 to build the thick layered film up to 300 um.

#### Key Features

- Compatible with AlN and Al2O3
- Excellent electrical and thermal properties
- Excellent fired film density
- High fired film thickness (up to 300 um) ENIG and ENEPIG plateable
- Wire bondable-thick Al wire



*This picture does not show the packaging of C7403 - C7404A and is solely intended for illustration purposes. The products are available in different packaging configurations and may change over time. Please refer to the latest safety data sheets for safety-relevant pictograms.*

#### Typical Properties

Viscosity	C7403: 120-220 Kcps C7404A: 150-250 Kcps Brookfield HBT, SC4-14 at 10 rpm, 25 °C
Alloy Ratio	100
Metal	Cu

#### Recommended Processing Guide

Process Temperature (TDS)	Fire in Nitrogen with O2 between 2-10 ppm 925-950 °C peak. Dwell time of 8-10 minutes.
Film Thickness	5 layers of C7404A can be printed to achieve a fired film thickness of up to 300 um.

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